

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0015477658](#)  
**Status:** **Active**  
**Description:** 2.54mm (.100") Pitch C-Grid® Header, Through Hole, Dual Row, Vertical, High Temperature, Shrouded, with Peg, 58 Circuits, 0.38µm (15µ") Gold (Au) Selective Plating, Tin (Sn) PC Tail Plating

**Documents:**

[3D Model](#) [Product Specification PS-70567 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**Agency Certification**

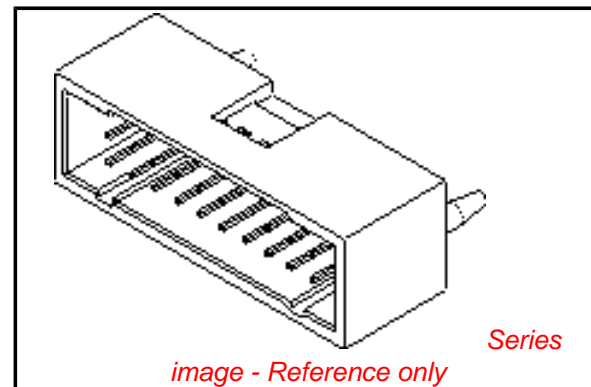
CSA LR19980  
 UL E29179

**General**

Product Family PCB Headers  
 Series [70568](#)  
 Application Wire-to-Board  
 Product Name C-Grid®

**Physical**

Breakaway No  
 Circuits (Loaded) 58  
 Color - Resin Black  
 First Mate / Last Break No  
 Flammability 94V-0  
 Glow-Wire Compliant No  
 Guide to Mating Part No  
 Keying to Mating Part None  
 Lock to Mating Part Yes  
 Material - Metal Brass, Phosphor Bronze  
 Material - Plating Mating Gold  
 Material - Resin High Temperature Thermoplastic  
 Number of Rows 2  
 Orientation Vertical  
 PC Tail Length (in) 0.130 In  
 PC Tail Length (mm) 3.30 mm  
 PCB Locator No  
 PCB Retention Yes  
 PCB Thickness Recommended (in) 0.093 In  
 PCB Thickness Recommended (mm) 2.40 mm  
 Packaging Type Tube  
 Pitch - Mating Interface (in) 0.100 In  
 Pitch - Mating Interface (mm) 2.54 mm  
 Pitch - Term. Interface (in) 0.100 In  
 Pitch - Term. Interface (mm) 2.54 mm  
 Plating min: Mating (µin) 15  
 Plating min: Mating (µm) 0.38  
 Polarized to Mating Part Yes  
 Polarized to PCB Yes  
 Shrouded Fully  
 Stackable No  
 Surface Mount Compatible (SMC) No  
 Temperature Range - Operating -55°C to +105°C  
 Termination Interface: Style Through Hole



**EU RoHS**

**ELV and RoHS Compliant**  
**REACH SVHC Contains SVHC: No**  
**Halogen-Free Status**

**China RoHS**



**Not Reviewed**

**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**  
[70568Series](#)

**Electrical**

Current - Maximum per Contact 2.5A  
Voltage - Maximum 250V

**Solder Process Data**

Duration at Max. Process Temperature (seconds) 5  
Lead-free Process Capability SMC & Wave Capable (TH only)  
Max. Cycles at Max. Process Temperature 1  
Process Temperature max. C 245

**Material Info**

Old Part Number A-70568-0061

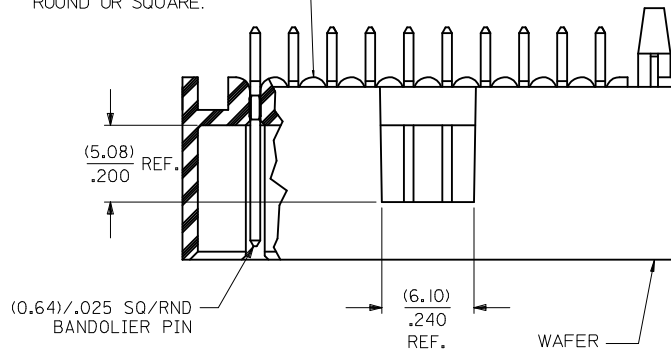
**Reference - Drawing Numbers**

Product Specification PS-70567  
Sales Drawing SDA-70568-\*\*\*\*

This document was generated on 03/31/2010

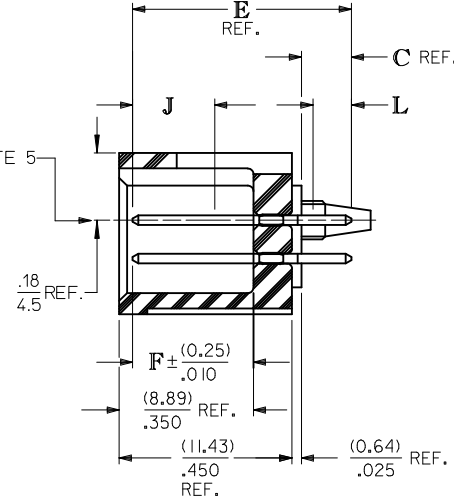
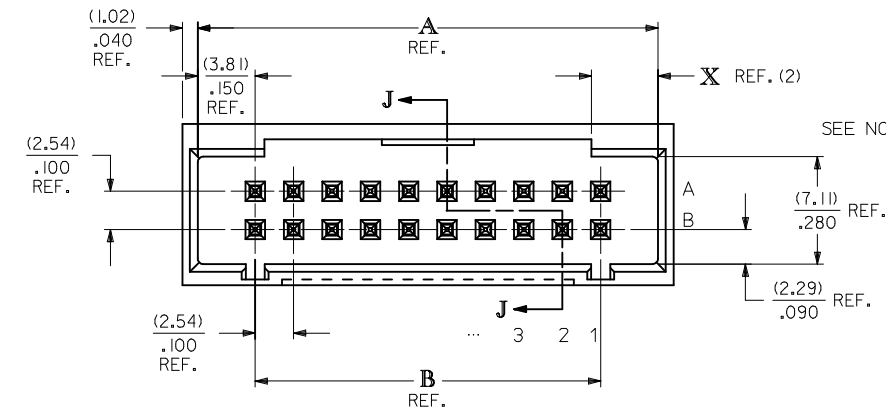
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STAND OFFS CAN BE EITHER ROUND OR SQUARE.

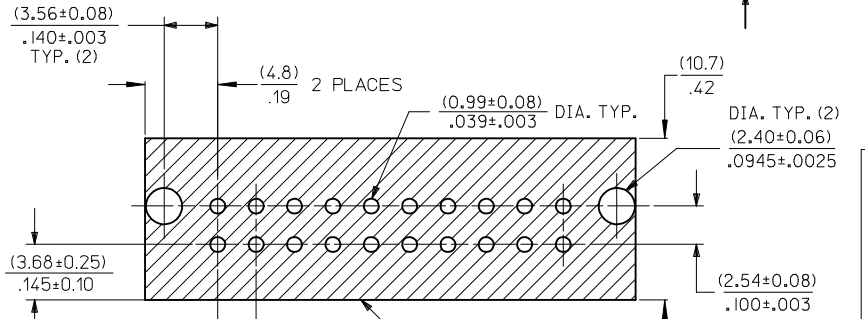
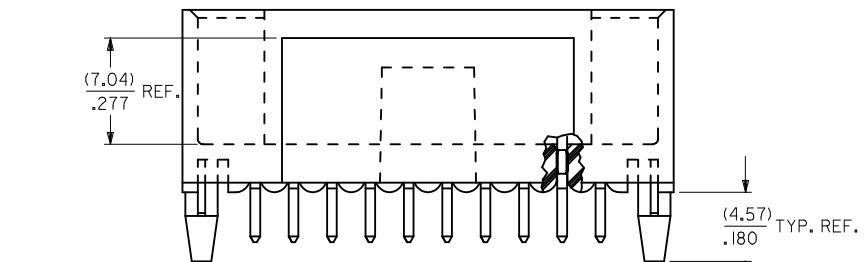


NOTES:

1. MATERIAL: WAFER - GLASS FILLED LIQUID CRYSTAL POLYMER, UL 94V-0, COLOR: BLACK, PIN: COPPER ALLOY.
2. PLATING: TIN  
 TIN(Sn) ALLOY OVER ENTIRE PIN: THICKNESS = (3.81 MICROMETER)/ 150 MICROINCH MINIMUM;  
 NICKEL (Ni) UNDERPLATE OVER ENTIRE PIN;  
 15 GOLD SELECTIVE GOLD (Au) IN THE CONTACT AREA: THICKNESS = (0.38 MICROMETER)/ 15 MICROINCH MINIMUM;  
 SELECTIVE TIN (Sn) ALLOY IN THE PC TAIL AREA: THICKNESS = (1.91 MICROMETER)/ 75 MICROINCH MINIMUM;  
 NICKEL (Ni) UNDERPLATE OVER ENTIRE PIN;  
 30 GOLD SELECTIVE GOLD (Au) IN THE CONTACT AREA: THICKNESS = (0.76 MICROMETER)/ 30 MICROINCH MINIMUM;  
 SELECTIVE TIN (Sn) ALLOY IN THE PC TAIL AREA: THICKNESS = (1.91 MICROMETER)/ 75 MICROINCH MINIMUM;  
 NICKEL (Ni) UNDERPLATE OVER ENTIRE PIN.  
 \* THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
3. PRODUCT SPECIFICATION: PS-70567.
4. PACKAGING: SEE CHARTS
5. PIN PUSHOUT FORCE: 4 LBS. MIN. IN DIRECTION INDICATED.
6. FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
7. PINS MUST MEET SOLDERABILITY SPEC. SMS-152.  
 EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN FAYING SURFACE. (APPROX. (0.64)/.025 LNG X (0.15)/.006 WD. REF.) - 2 LOCATIONS
8. NO FEATURES WHICH RISE ABOVE THE PCB SURFACE ALLOWED IN THIS AREA.
9. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002.



**SECTION J-J**



**RECOMMENDED P.C. BOARD HOLE LAYOUT**

CKT. SIZE	DIM. A REF.		DIM. B REF.		DIM. X REF.	
	(MM)	INCH	(MM)	INCH	(MM)	INCH
6	(12.70)	.500	(5.08)	.200	(3.18)	.125
8	(15.24)	.600	(7.62)	.300	(4.42)	.174
10	(17.78)	.700	(10.16)	.400	(4.42)	.174
12	(20.32)	.800	(12.70)	.500	(4.42)	.174
14	(22.86)	.900	(15.24)	.600	(4.42)	.174
16	(25.40)	1.000	(17.78)	.700	(4.42)	.174
18	(27.94)	1.100	(20.32)	.800	(4.42)	.174
20	(30.48)	1.200	(22.86)	.900	(4.42)	.174
22	(33.02)	1.300	(25.40)	1.000	(4.42)	.174
24	(35.56)	1.400	(27.94)	1.100	(4.42)	.174
26	(38.10)	1.500	(30.48)	1.200	(4.42)	.174
28	(40.64)	1.600	(33.02)	1.300	(4.42)	.174
30	(43.18)	1.700	(35.56)	1.400	(4.42)	.174
32	(45.72)	1.800	(38.10)	1.500	(4.42)	.174
34	(48.26)	1.900	(40.64)	1.600	(4.42)	.174
36	(50.80)	2.000	(43.18)	1.700	(4.42)	.174
38	(53.34)	2.100	(45.72)	1.800	(4.42)	.174
40	(55.88)	2.200	(48.26)	1.900	(4.42)	.174
42	(58.42)	2.300	(50.80)	2.000	(4.42)	.174
44	(60.96)	2.400	(53.34)	2.100	(4.42)	.174
46	(63.50)	2.500	(55.88)	2.200	(4.42)	.174
48	(66.04)	2.600	(58.42)	2.300	(4.42)	.174
50	(68.58)	2.700	(60.96)	2.400	(4.42)	.174
52	(71.12)	2.800	(63.50)	2.500	(4.42)	.174
54	(73.66)	2.900	(66.04)	2.600	(4.42)	.174
56	(76.20)	3.000	(68.58)	2.700	(4.42)	.174
58	(78.74)	3.100	(71.12)	2.800	(4.42)	.174
60	(81.28)	3.200	(73.66)	2.900	(4.42)	.174
62	(83.82)	3.300	(76.20)	3.000	(4.42)	.174
64	(86.36)	3.400	(78.74)	3.100	(4.42)	.174
66	(88.90)	3.500	(81.28)	3.200	(4.42)	.174
68	(91.44)	3.600	(83.82)	3.300	(4.42)	.174
70	(93.98)	3.700	(86.36)	3.400	(4.42)	.174
72	(96.52)	3.800	(88.90)	3.500	(4.42)	.174

2	G
1	H
SHT	REV

<b>MODIFIED NOTES</b> EC NO: UCP2009-0336 DRAWN: KLOSTERMAYER 2008/09/23 CHKD: JEBELL 2008/09/24 APPR: FSMITH 2008/09/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .005 2 PLACES ± 0.13 ± .01 1 PLACE ± 0.25 ± --- ANGULAR ± 1/2°	DIMENSION STYLE MM/IN DRAWN BY DATE SMR 1993/11/10 CHECKED BY DATE SMR 1993/11/10 APPROVED BY DATE	SCALE 4:1 DESIGN UNITS INCH THIRD ANGLE PROJECTION	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE SIZE C	DOCUMENT NO. SDA-70568-**** SHEET NO. 1 OF 2	MOLEX INCORPORATED
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			SALES ASSY - DUAL ROW SHROUDED WAFER/HI TEMP .25SQ/RND PINS .100 GRID
		MOLEX INCORPORATED			

